

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT

**CONVEYING PARTY DATA**

Name	Execution Date
JIAN DAI	07/17/2020
PENGFEI ZUO	07/17/2020
WENYU YE	08/04/2020
ZEHONG GUAN	07/17/2020
MING LI	07/17/2020

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**PROPERTY NUMBERS Total: 1**

Property Type	Number
<b>Application Number:</b>	16963211

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<b>NAME OF SUBMITTER:</b>	JIAYU SONG
<b>SIGNATURE:</b>	/Jiayu Song/
<b>DATE SIGNED:</b>	08/06/2020
<b>Total Attachments: 3</b> source=10038-01-0038-US-Assignment-signed#page1.tif source=10038-01-0038-US-Assignment-signed#page2.tif source=10038-01-0038-US-Assignment-signed#page3.tif	

## ASSIGNMENT

I/WE, **Jian DAI, Pengfei ZUO, Wenyu YE, Zehong GUAN and MingLI** are inventor(s) (hereinafter referred to as the Assignor(s)) of an invention known as:

### **METHOD FOR ANALYZING ARRHYTHMIA IN REAL TIME, ELECTROCARDIOGRAM MONITORING DEVICE AND STORAGE MEDIUM**

as disclosed and claimed in the application(s) of:

<b>Application Number</b>	<b>Country of Filing</b>	<b>Filing Date</b>
PCT/CN2018/073252	WO	January 18, 2018
16/963,211	US	July 18, 2020

**SHENZHEN MINDRAY BIO-MEDICAL ELECTRONICS CO., LTD.**, a corporation formed under the laws of China, whose mailing address is Mindray Building, Keji 12th Road South, Hi-tech Industrial Park, Nanshan, Shenzhen, P.R. China, 518057, and **Shenzhen Mindray Scientific Co., Ltd.**, a corporation formed under the laws of China, whose mailing address is 6/F, Bldg 2, 1203 Nanhuan Avenue, Yutang Block, Guangming District, Shenzhen, P. R. China (hereafter referred to as the Assignees).

In consideration of the sum of One Dollar (\$1.00) or equivalent and other good and valuable consideration the receipt of which from the Assignees is hereby acknowledged, I/WE, as the Assignor(s), hereby sells and assigns to the Assignees, the entire right, title and interest, including the right to sue for past infringement and to collect for all past, present and future damages, for the United States of America (as defined in 35 U.S.C. § 100) and throughout the world,

(a) in this invention listed above, in any and all applications for patents filed or may be filed on this invention in all countries throughout the world, including any PCT International Application and all national stage applications based thereon, and all patents issued upon such applications in all countries throughout the world, and

(b) in any and all applications in any country that claim the benefit of the patent application listed above, including non-provisional applications, continuing (continuation, divisional, or continuation-in-part) applications, reissues, extensions, renewals and reexaminations of the patent application or Letters Patent therefor listed above, and all rights to claim priority in any country on the basis of any such applications, and all extensions, renewals, and reissues thereof, to the full extent of the term or terms for which Letters Patents issue, and

(c) in any and all inventions described in the patent application listed above, and in any and all forms of intellectual and industrial property protection derivable from such patent application, and that are derivable from any and all continuing

applications, reissues, extensions, renewals and reexaminations of such patent application, including, without limitation, patents, applications, utility models, inventor's certificates, and designs together with the right to file applications therefor; and including the right to claim the same priority rights from any previously filed applications under the International Agreement for the Protection of Industrial Property, or any other international agreement, or the domestic laws of the country in which any such application is filed, as may be applicable;

all such rights, title and interest to be held and enjoyed by the above-named Assignees, their successors, legal representatives and assigns to the same extent as all such rights, title and interest would have been held and enjoyed by the Assignors had this assignment and sale not been made.

The undersigned inventor(s) hereby authorizes and requests that any official of any country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignees, their successors and assigns, in accordance with the terms of this Assignment.

The undersigned inventor(s) agrees to execute all papers necessary in connection with the application(s) and any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue, reexamination or corresponding application(s) thereof and also to execute separate assignments in connection with such application(s) as the Assignees may deem necessary or expedient.

The undersigned inventor(s) agrees to execute all papers necessary in connection with any interference or patent enforcement action (judicial or otherwise) related to the application(s) or any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue or reexamination application(s) thereof and to cooperate with the Assignees in every way possible in obtaining evidence and going forward with such interference or patent enforcement action.

The undersigned inventor(s) hereby represents that he/she has full right to convey the entire interest herein assigned, and that he/she has not executed, and will not execute, any agreement in conflict therewith.

The undersigned inventor(s) hereby grants the patent practitioners associated with **CUSTOMER NUMBER 153988** the power to insert in this assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

The undersigned inventor(s) hereby represents that he/she understands that the patent practitioners associated with **CUSTOMER NUMBER 153988** are the legal representatives of, and attorneys for, the Assignees, and are NOT the legal representatives of, and attorneys for, the inventor(s).

The undersigned Assignees hereby agree that all rights, title and interest assigned by the inventor(s) by this Assignment are to be held and enjoyed in equal shares (i.e., in 50%-50% shares) by the Assignees, their respective successors, legal representatives and assigns. Each Assignee is entitled to assign, license, or otherwise transfer their respective shares.

IN WITNESS WHEREOF, executed by the undersigned inventor(s) on the date opposite his/her name.

Date: 2020.7.17 Signature of Inventor: Jian Dai  
Jian DAI

Date: 2020.7.17 Signature of Inventor: Pengfei Zuo  
Pengfei ZUO

Date: 2020.8.04 Signature of Inventor: Ye Wenyu  
Wenyu YE

Date: 2020.7.17 Signature of Inventor: Zehong GUAN  
Zehong GUAN

Date: 2020.7.17 Signature of Inventor: MingLI  
MingLI

**ASSIGNEE: SHENZHEN MINDRAY BIO-MEDICAL ELECTRONICS CO., LTD.**

Signature: Du Du

Printed Name: Jianguang Du

Corporate Title: IP Director

Date: August 5, 2020

**ASSIGNEE: SHENZHEN MINDRAY SCIENTIFIC CO., LTD.**

Signature: Du Du

Printed Name: Jianguang Du

Corporate Title: IP Director

Date: August 5, 2020